

REFLOW SOLDERING CONDITIONS 回流焊条件

Applicable to Chip Type Aluminum Electrolytic Capacitors 适用于贴片式铝电解电容器

Recommended Conditions for Reflow Soldering (推荐回流焊条件)

(1) A thermal condition system such as infrared radiation (IR) or hot blast shall be adopted, and vapor heat transfer systems(VPS) are not recommended.

应采用红外线及热风回流焊接，不宜采用汽相加热回流焊接；

(2) Reflow soldering should be performed one time. If the capacitor has to be reflowed twice, 30 minutes must be layout between each time.

推薦回流焊只進行一次，回流焊次數如果需要二次，必須相隔30分鐘以上；

(3) The time of preheating from 150° C to 200° C shall be within maximum 180 seconds;

從150°C至200°C的預熱時間在180秒鐘以內；

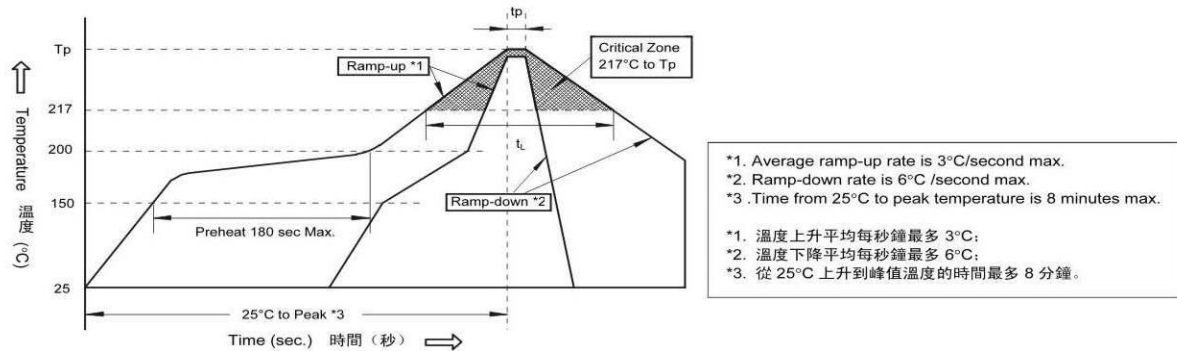
(4) The time of soldering at 217° C measured on capacitors' top shall not exceed tL (second);

電容器頂部溫度超過217°C的焊接時間不超過 tL 秒；

(5) The peak temperature on capacitors' top shall not exceed Tp(° C), and the time within 5° C of actual peak temperature shall not exceed tp (second).

電容器頂部尖峰溫度不超過 Tp°C，在5°C範圍內的實際尖峰溫度時間不超過 tp 秒

Classification Reflow Profile

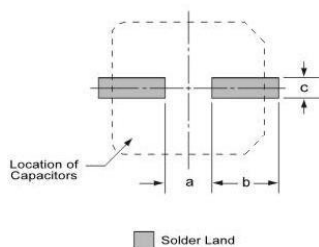


Classified at Temperature and Time Only for Standard Size without ()

Size	Thickness(mm) 厚度	Volume(mm ³) 体积	Tp ()	TL (second)	Tp (second)
Φ4~Φ6.3, Φ8×6.2L	• ≥2.5	<350	250±0	60	5
Φ8×10.5L	• ≥2.5	350~2000	240±0	60	5
Φ10×10.5L/13.5L	• ≥2.5	350~2000	235±0	60	5
Φ12.5, Φ16	≥2.5	>2000	230±0	30(20*)	5

Re: (20*) is special for mid-to-high voltage which is HU series. 注：(20*)为针对中高压 HU 系列产品

Recommended Solder Land Size no PC Board(Unit: mm)



Size 尺寸	a	b	c
Ø4	1.0	2.6	1.6
Ø5	1.4	3.0	1.6
Ø6.3	2.1	3.5	1.6
Ø8×6.2L	2.1	4.5	1.6
Ø8×10.5L	3.0	3.5	2.5
Ø10	4.0	4.0	2.5
Ø12.5	4.0	5.7	3.0
Ø16	6.0	6.5	3.5

NOTE: All designs and specifications are for reference only and are subject to change without prior notice. If any doubt about safety for your application, please contact us immediately for technical assistance before purchase.

注：以上所提供的設計及特性參數僅供參考，任何修改不作預先通知。如果在使用上有疑問，請在採購前與我們聯繫，以便提供技術上的協助